PRODUCT PROFILE:





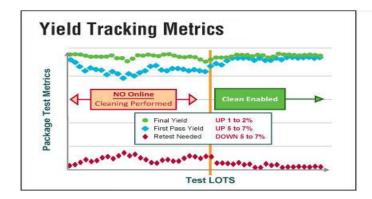
Improve Your Yields Through Innovation

International Test Solutions provides non-destructive cleaning products used by semiconductor manufacturers to remove debris and contaminants generated during wafer level and burn-n/test socket testing. By removing loose debris and adherent contaminants in-line, the quality of the testing data is improved, the test equipment downtime is reduced, throughput is increased and manufacturing yields are improved.

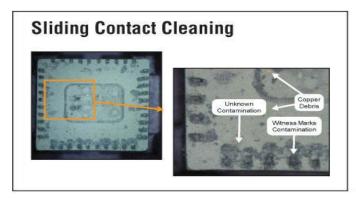
Test Cell Conditioner®

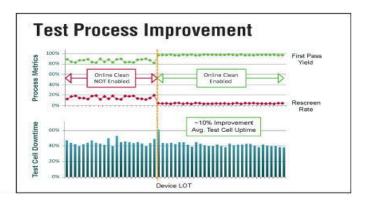
Increases First Pass and Improves Handler Uptime

Test Cell Conditioner® (TCC) is a patented turnkey cleaning unit designed to remove loose debris as well as embedded oxides from test socket and contactors. Sometimes called a surrogate cleaning device, or SCD, it facilitates frequent on-line socket cleaning without the need for equipment downtime or operator intervention. All the major handler suppliers now offer programmable auto clean functions capable of using the TCC devices for regular socket cleaning without downtime. TCC products use customized polymers installed onto ESD safe substrates. With appropriate material selection, the TCC products can be used for sliding and spring type contactors and are the only on-line cleaning solution in tri-temperature handlers at-50C to 160C. Debris and contaminants are collected without the risk of damage to the contactors, base metal, or surface plating; thereby, maximizing socket life and test throughput. Since over 70% of device yield fallout and re-screen can be attributed to electrical contact related issues, implementation of auto-cleaning using engineered TCC units is critical for lowering COT and maintaining high UPH metrics.









Represented in the UK and Ireland by, SiSTEM Technology